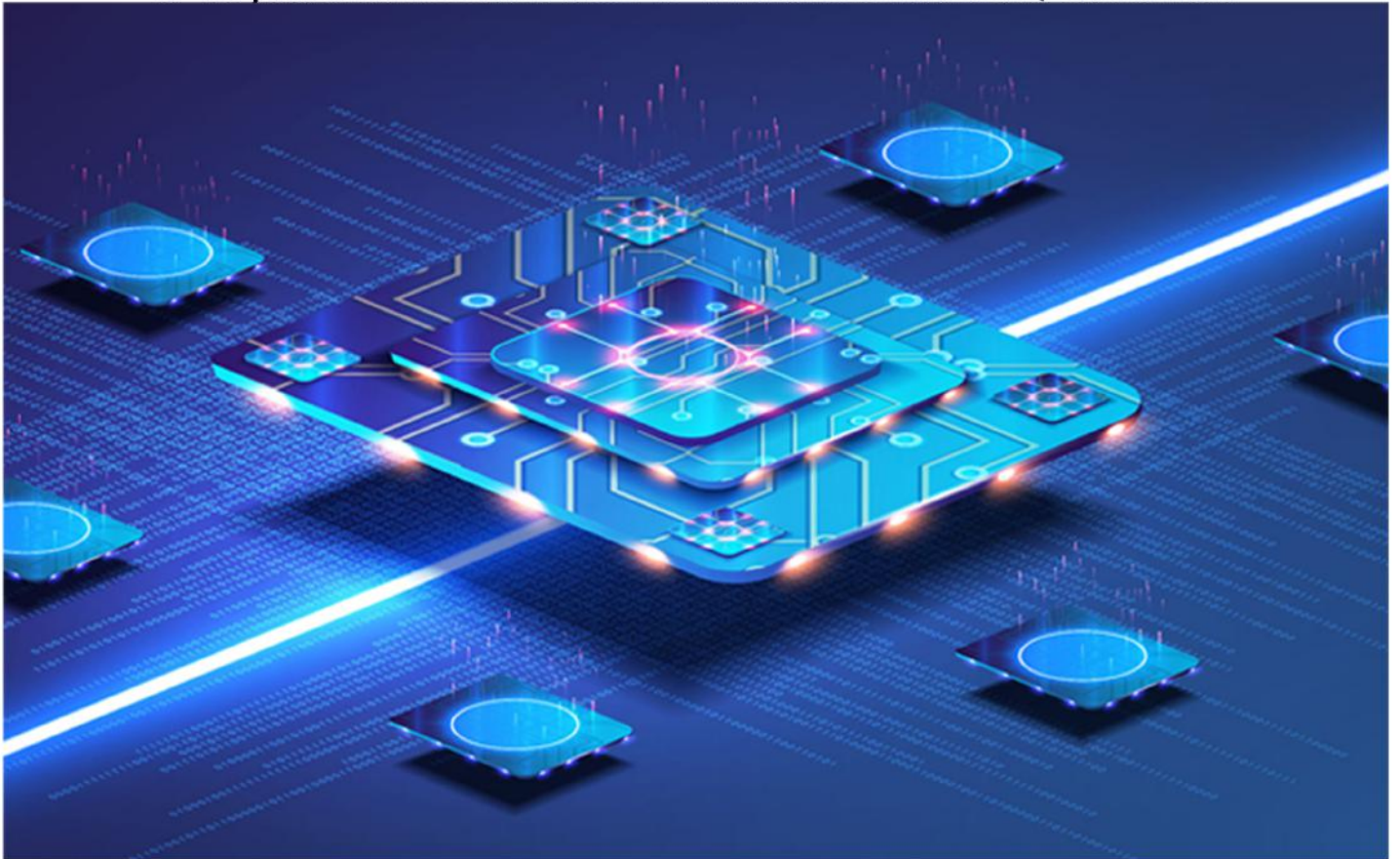


# Call for Book Chapters/Research Papers for Edited Book

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Paper submission portal opens from 12<sup>th</sup> June 2023

Last date for chapter submission: within 31<sup>st</sup> July 2023

Review status notification: within 31<sup>st</sup> July 2023

(Parallel Process)

Last date for resubmission/extended submission: 28<sup>th</sup> August  
2023

Final Acceptance Notification: within 2<sup>nd</sup> September 2023

Last date for registration: within 14<sup>th</sup> October 2023

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# Call for Chapters Futuristic Trends in Artificial Intelligence

Book series ID: IIPV3EBS09\_G26

Submit chapter at: [www.iipseries.org](http://www.iipseries.org)

Last date for chapter submission: 28<sup>th</sup> August 2023

Publication month: December 2023

## AIM & SCOPE

A major objective of this book series is to drive innovation in every aspect of Artificial Intelligence. It offers researchers, educators and students the opportunity to discuss and share ideas on topics, trends and developments in the fields of artificial intelligence, machine learning, deep learning and more, big data and computer science, computer intelligence and Technology. It aims to bring together experts from various disciplines to emphasize the dissemination of ongoing research in the fields of science and computing, computational intelligence, schema recognition and information retrieval. Articles are requested that describe original work in the below areas and related technologies but not limited to

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2. Robotics including Autonomous Guidance Applications
3. Video Surveillance and Related Applications
4. Image Retrieval and Visual Search
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6. Image and Video Communications
7. Bio-medical and Medical imaging
8. Remote Sensing
9. Natural Language Processing
10. Fuzzy Systems
11. Block Chain
12. Applications from the following fields:
  13. Smart sensors
  14. Big Data
  15. Visualization
  16. Assisted Living for the Aging Population
  17. Medical and Biomedical Applications
  18. Commercial Development
  19. Energy Harvesting
  20. Industrial Applications
  21. Internet of Things
  22. Sensors for Aerospace
  23. Non-Destructive Evaluation
  24. Remote Sensing
  25. Smart Agriculture
  26. Smart Buildings Smart Cities and Communities
  27. Electrical and Electronic Materials and Process
  28. Semiconductor Technology
  29. Power Systems and Energy Engineering
  30. Soft Computing Techniques in Power Systems
  31. Transmission and Distribution System and Apparatus
  32. Instrumentation & Feedback Control Systems
  33. Power Electronics & Energy Efficient Drives
  34. Renewable Power Conversion Technologies
  35. Power Quality Improvement Techniques
  36. Electrical Machines and Industry Applications
  37. Bio-medical Engineering
  38. Intelligent Systems
  39. High Voltage Engineering & Insulation Technology
  40. Photo / Opto Electronics
  41. Geo-informative Systems
  42. Grid Computing
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